

**WHAT IS CLAIMED IS:**

1. A chip-type semiconductor light-emitting device, comprising:

a substrate;

a pair of electrodes formed on said substrate;

5 a semiconductor light-emitting chip electrically connected to said pair of electrodes;

a mold encapsulating respective parts of said semiconductor light-emitting chip and said pair of electrodes; and

10 a step formed in said electrodes at an inside of said mold and having a height increasing from an outer side to an inner side thereof.

2. A chip-type semiconductor light-emitting device according to claim 1, wherein said electrode includes a Cu layer, and said step being formed by changing a wall thickness of said Au layer.

15 a 3. A chip-type semiconductor light-emitting device according to claim 1 or 2, wherein said electrode includes an Au layer formed in an uppermost layer thereof.

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